

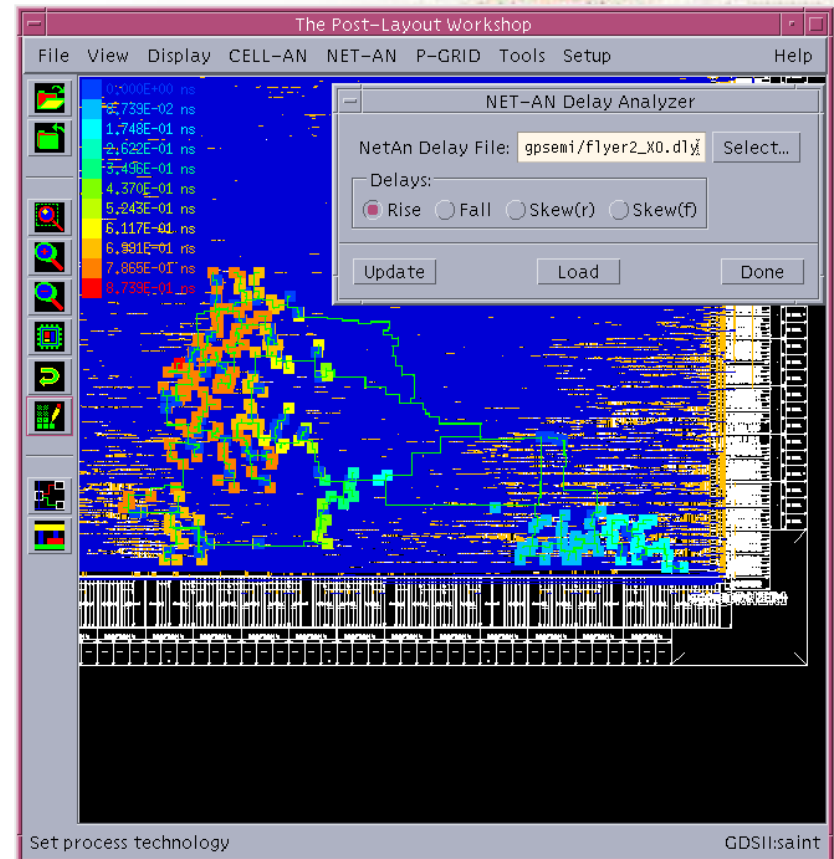


The Gold Standard for
Parasitic Extraction and
Signal Integrity Solutions

NET-AN

Critical Net Extraction and Analysis

- Full 3D seamless field solution
 - High accuracy extraction
 - Extracts net, tree, or entire path
 - Extracts with full net coupling
 - Outputs distributed RCLM SPICE circuit, dspf, spef, or sdf
- Easy to Use
 - Push-button hierarchical extraction
 - Graphical display of delays
 - Graphical net/cell browser
 - GDSII, P&R flow integration
 - Interactive or batch operation

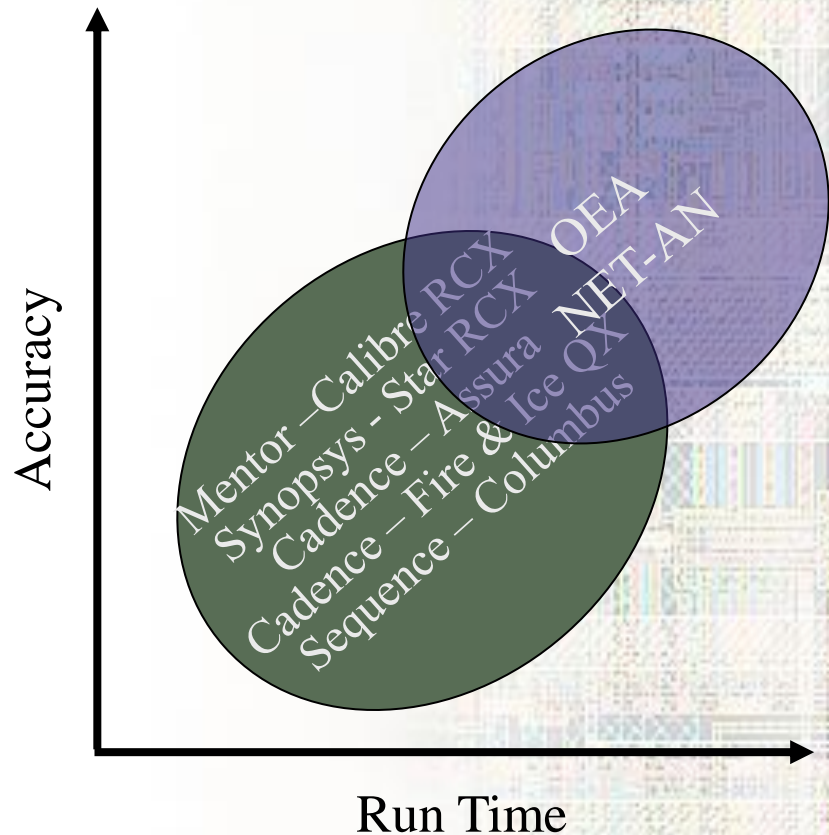


When do you need NET-AN?

- On nets that should be 'Designed' and not left up to the router
 - Clock Nets
 - High Speed Buses
- On nets that you know must be analyzed more closely
 - Top level clock trees
 - High speed buses
 - Critical or marginal timing paths
 - Other long and/or wide nets

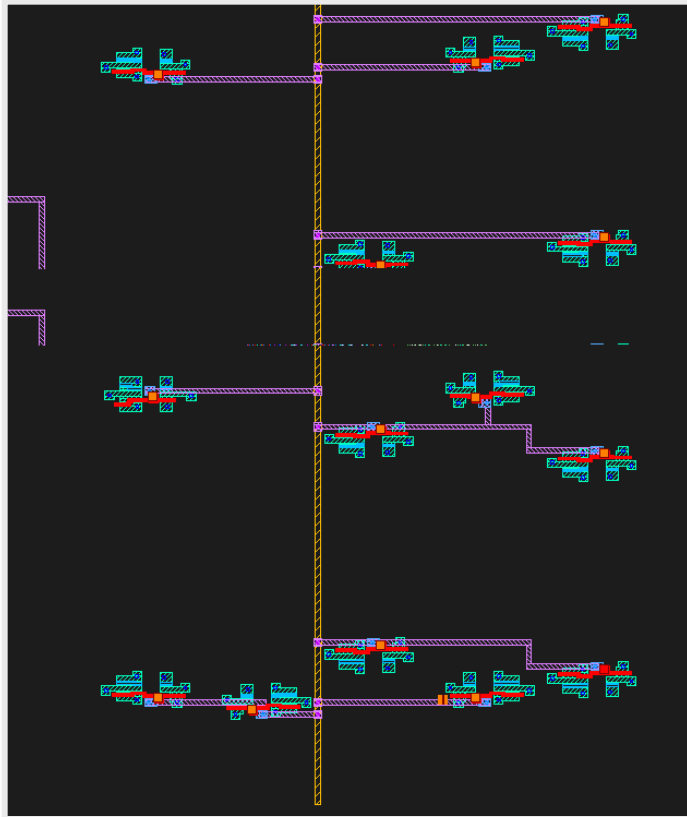
NET-AN Market Position

- **All extractors tradeoff accuracy vs. runtime!**
- **Pattern-based extraction**
 - Significant accuracy loss at boundaries
 - Requires rich pattern library
 - Not suited for critical nets analysis
- **Formula-based extraction**
 - Requires process dependent parameter tuning
 - Accuracy of methodology limited
 - Most widely all-net solution
- **Full 3D field solver (NET-AN)**
 - Delivers more exact solution
 - Fits critical net analysis & design needs



NET-AN

How it creates the 3D Model



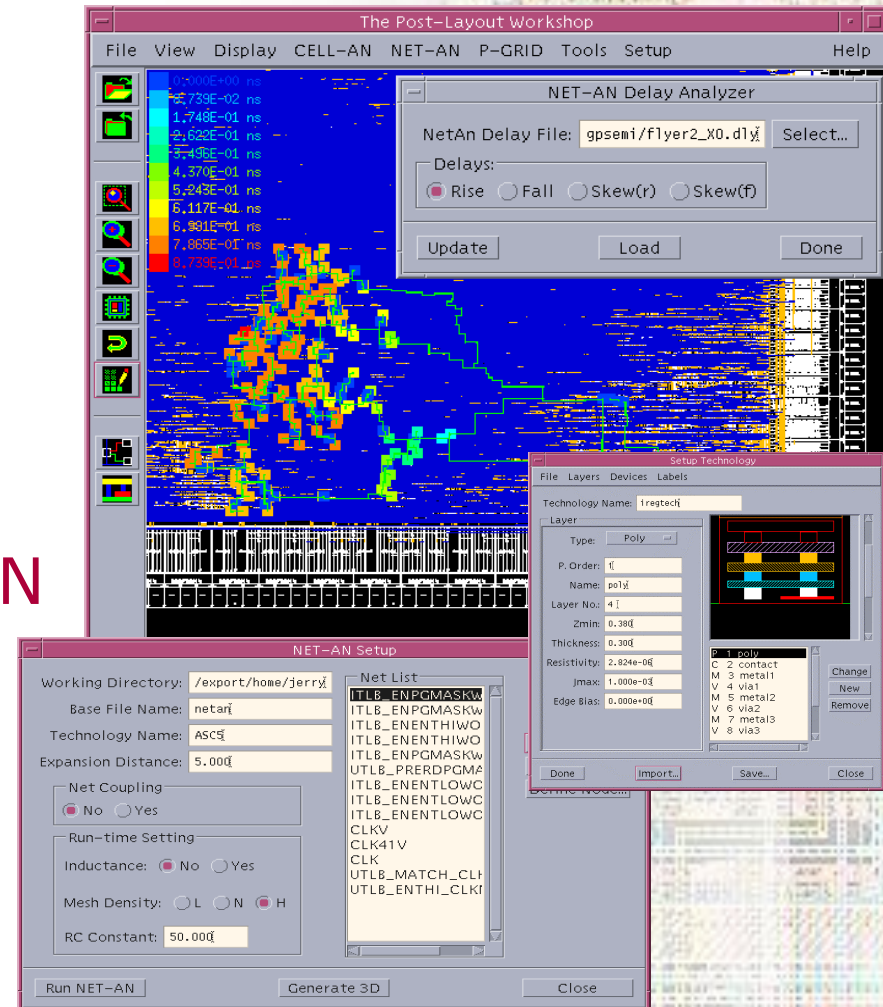
One or more 'Target Nets' are identified in the layout. This can be through an XY, layer, net name, or GDSII Reference file.



A 3D model is created with a 'Extraction Halo' for capacitance to neighbors. Inductance coupling is determined by a minimum coupling value.

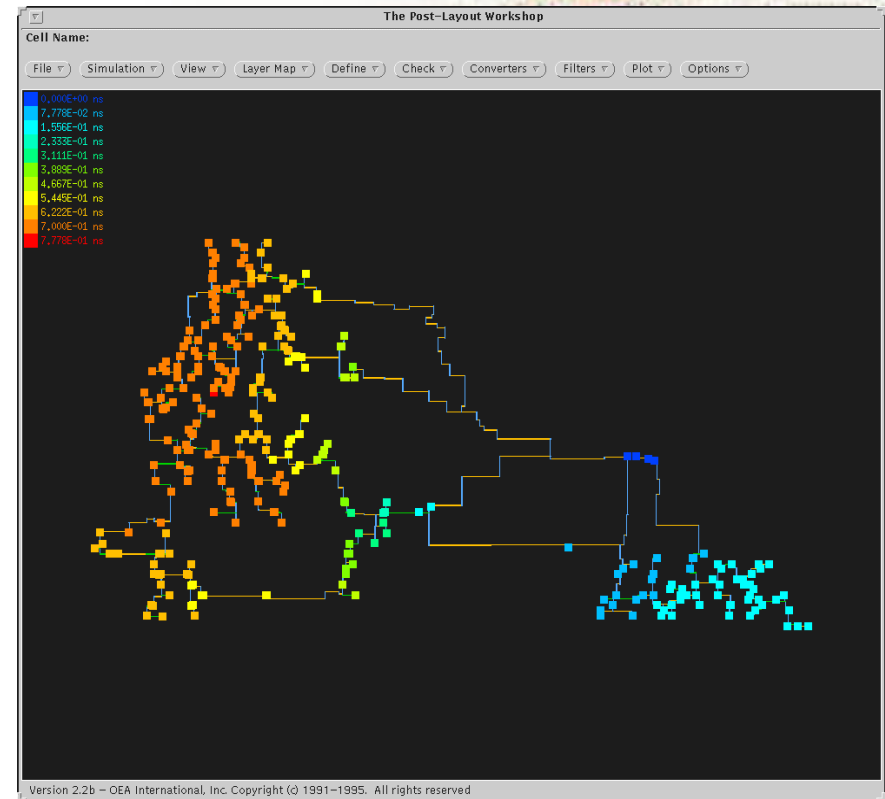
Post-Layout WorkShop (PLWS) OEA's Graphical User Interface

- Hierarchical GDSII input
 - Creates full-chip transistor-level connectivity
- Hierarchical net browser
 - User-assigned SPICE nodes
- Builds 3D model for NET-AN
 - Includes critical nets & surrounding metal



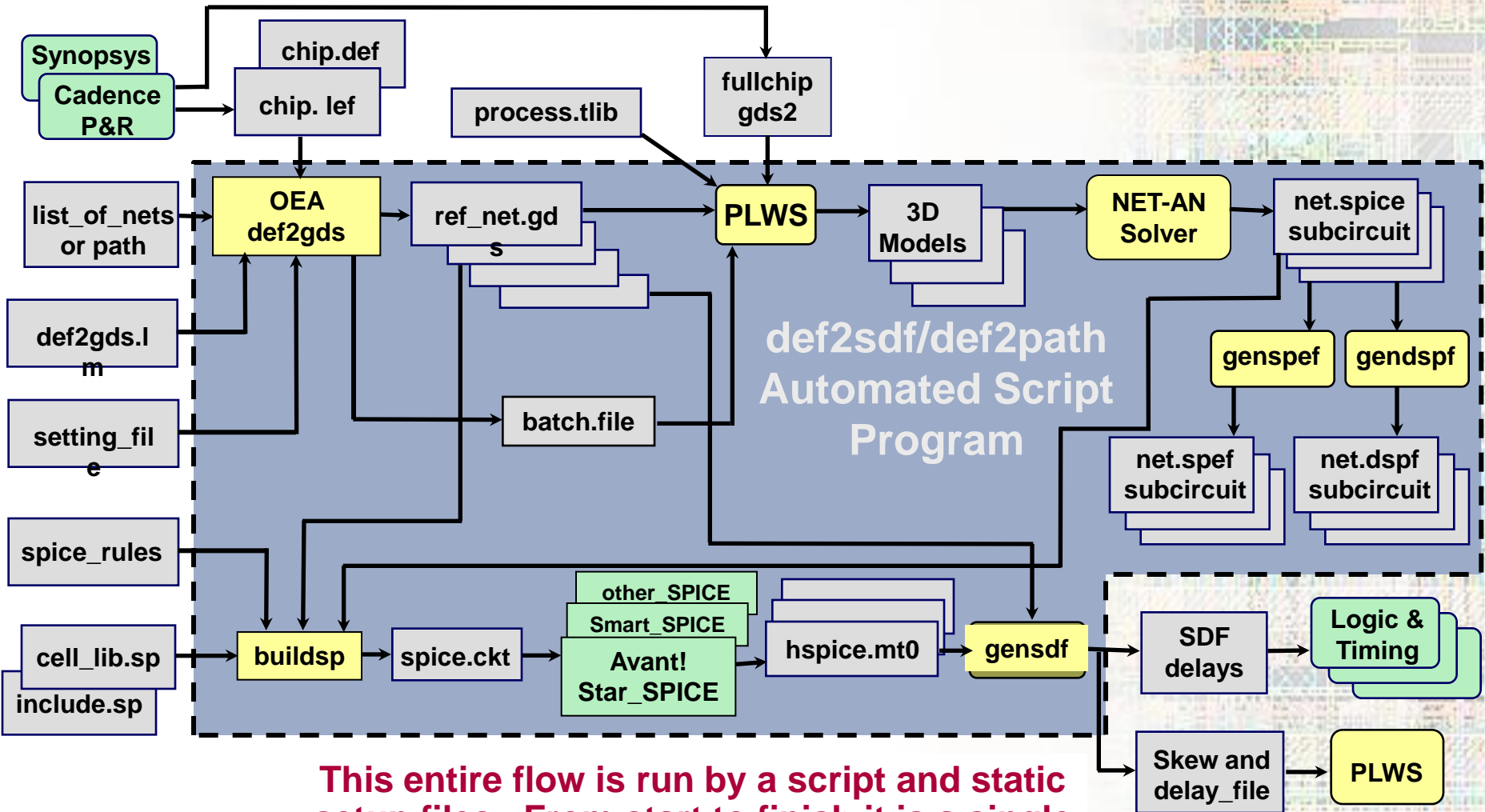
PLWS Post-Layout Critical Path Analysis

- Context Sensitive Display
 - Color coded critical paths
- NET-AN SPICE Deck Generation
 - Compact PI-model based upon user selected RC time constant
 - No further RC reduction required!
 - Ensures fast SPICE simulations



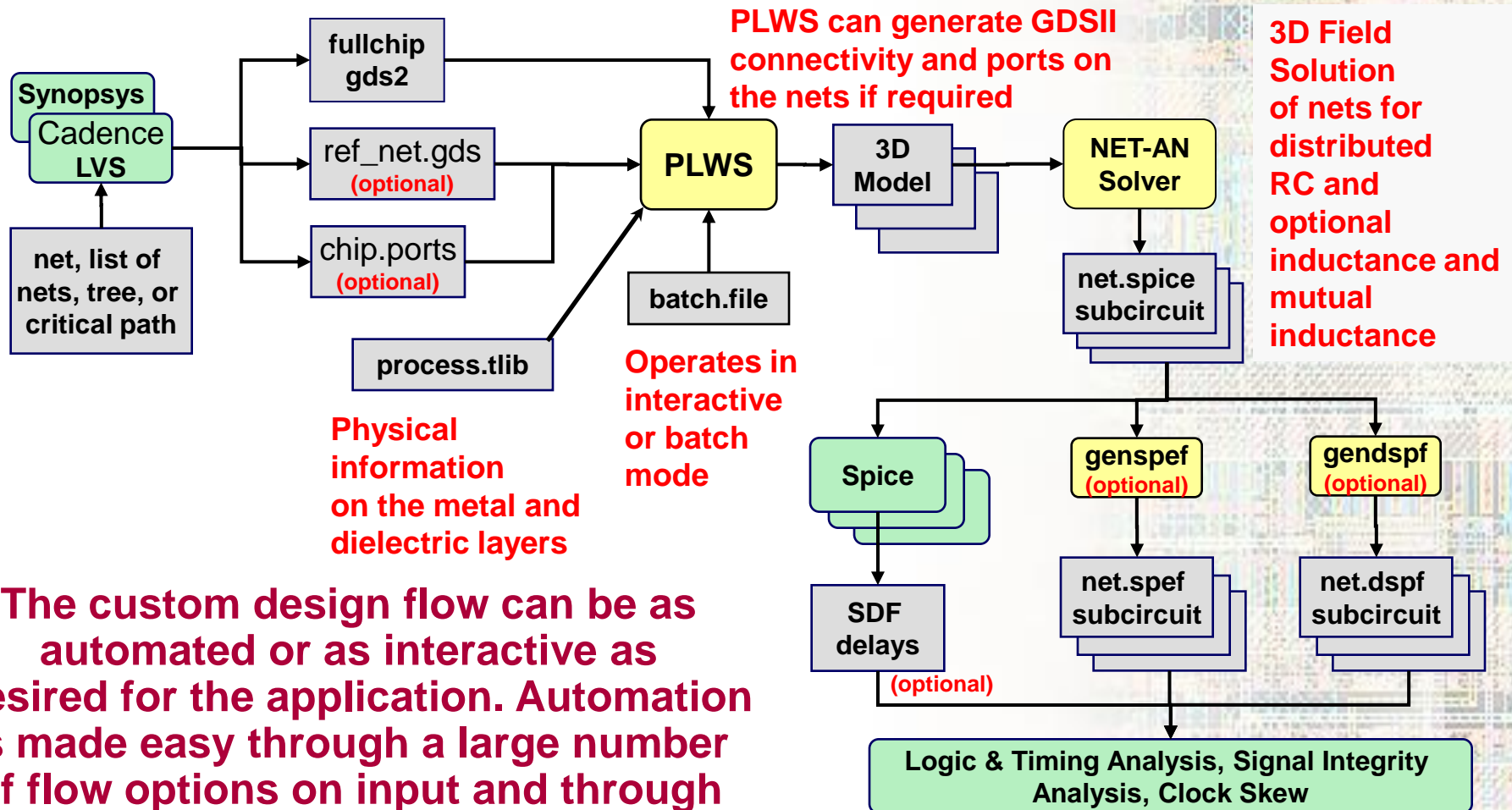
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Automatic Critical Net Analysis for P&R Design Flows



NET-AN

Custom Design Flow



Calculating Resistance The Right Way!

- Wrong Way

- Square counting yields errors for irregular conductor shapes
 - No width dependent resistivity support

- Right Way

- Find equipotential surface
- Solve for 3D resistance and inductance integrated with capacitance

$$R = V / I$$

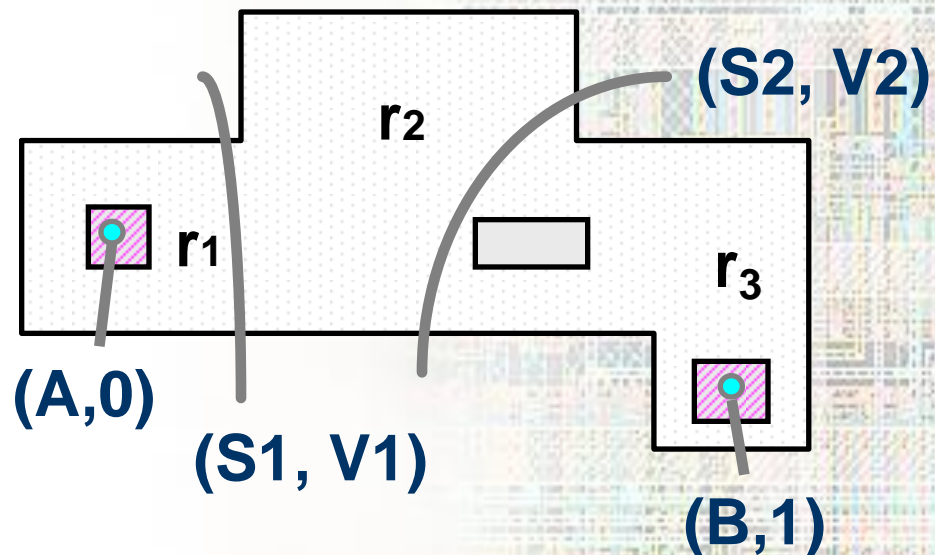
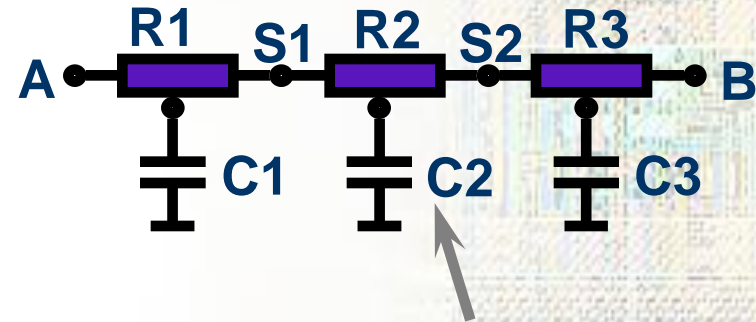
$$\nabla \cdot \vec{J} = 0$$

$$\vec{J} = \sigma \vec{E}$$

$$\vec{E} = -\nabla V$$

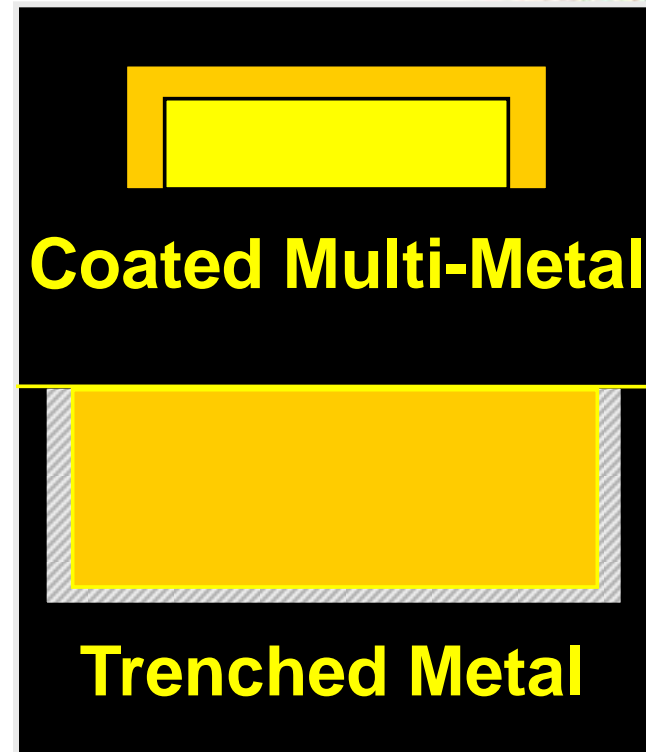
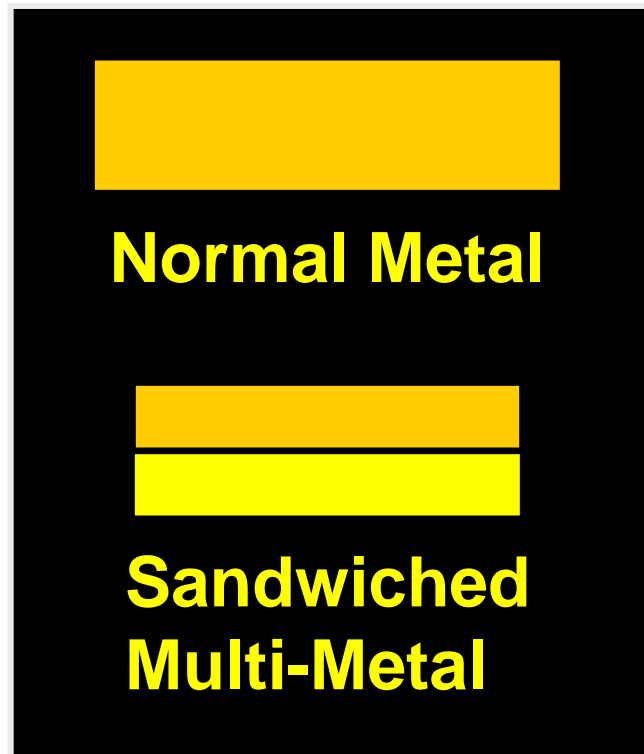
$$\nabla(\sigma \nabla V) = 0$$

$$I = \iint_S \vec{J} \cdot d\vec{s}$$



NET-AN

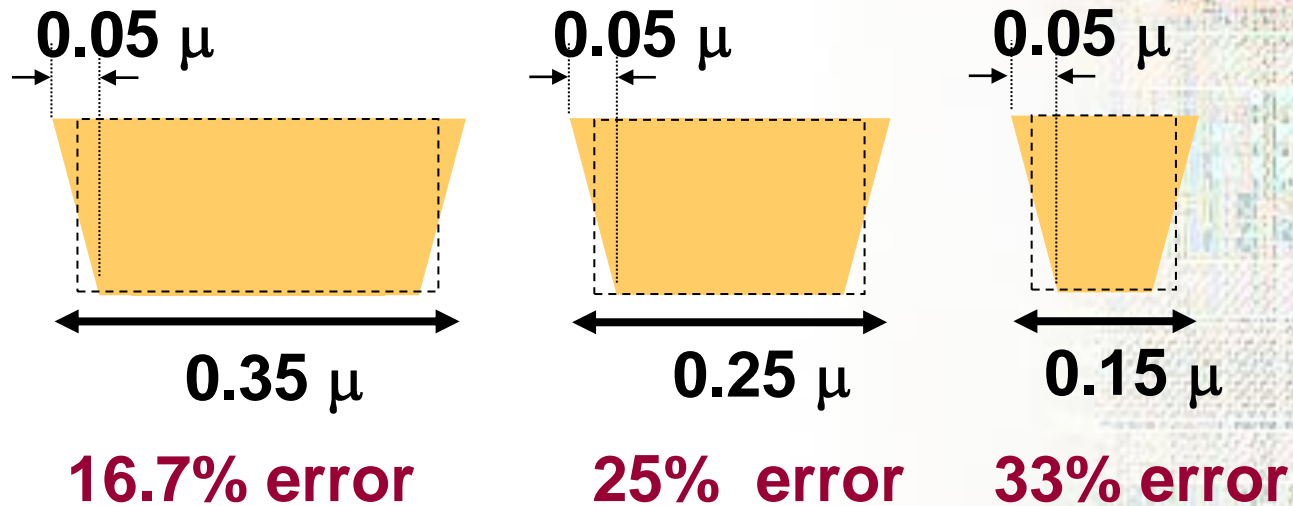
Width Dependent Resistivity Support



- **Coating/trench metals resistivity differ from conductor**
 - For narrow wires, coating has proportionately larger effect
- **Wire width sensitivities**
 - Wider wires experience electron scattering at/near surface
- **Mechanical polishing induces dishing of wide wires**
 - Copper processes exceptionally susceptible

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Layer Biasing Support



- Real wires are trapezoids!
 - Trapezoid angle varies based on metal width/spacings
 - True cross sectional area modeled correctly
 - True resistance extracted!

NET-AN

Full 3D Net Capacitance Extraction

- Full Maxwell field solution!

- No formula-based equations
- No reduced order equations

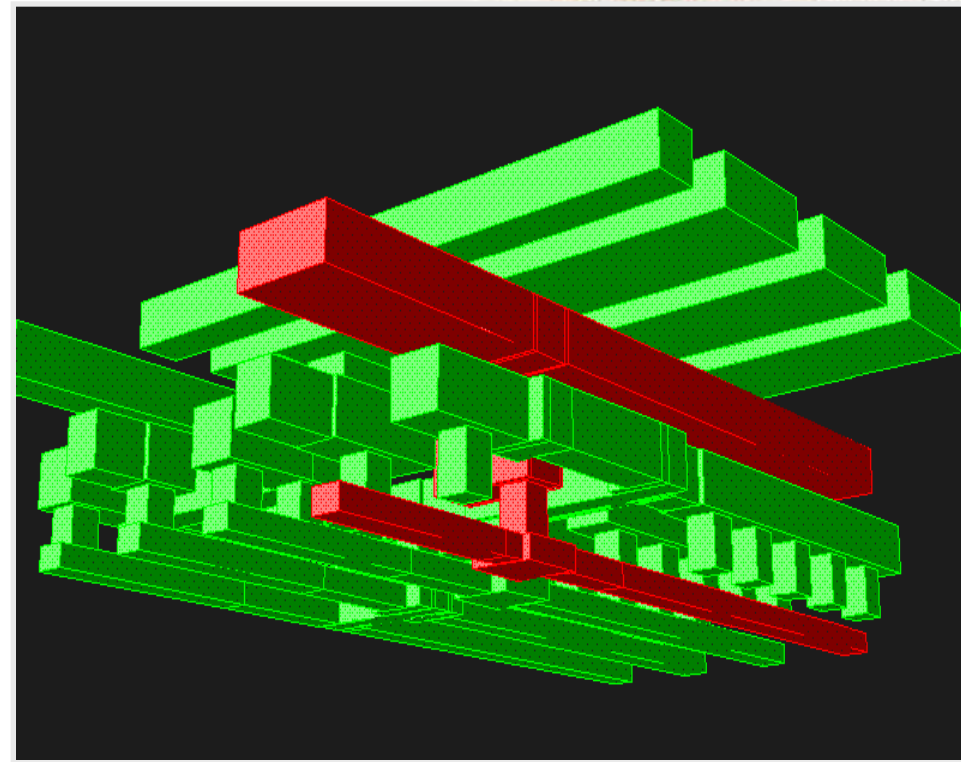
$$C = Q / V$$

$$\vec{D} = \epsilon \vec{E}$$

$$\nabla(\epsilon \nabla V) = \rho$$

$$Q = \iiint_{\Omega} \rho dV = \oint_{\Gamma} \vec{D} \cdot d\vec{s}$$

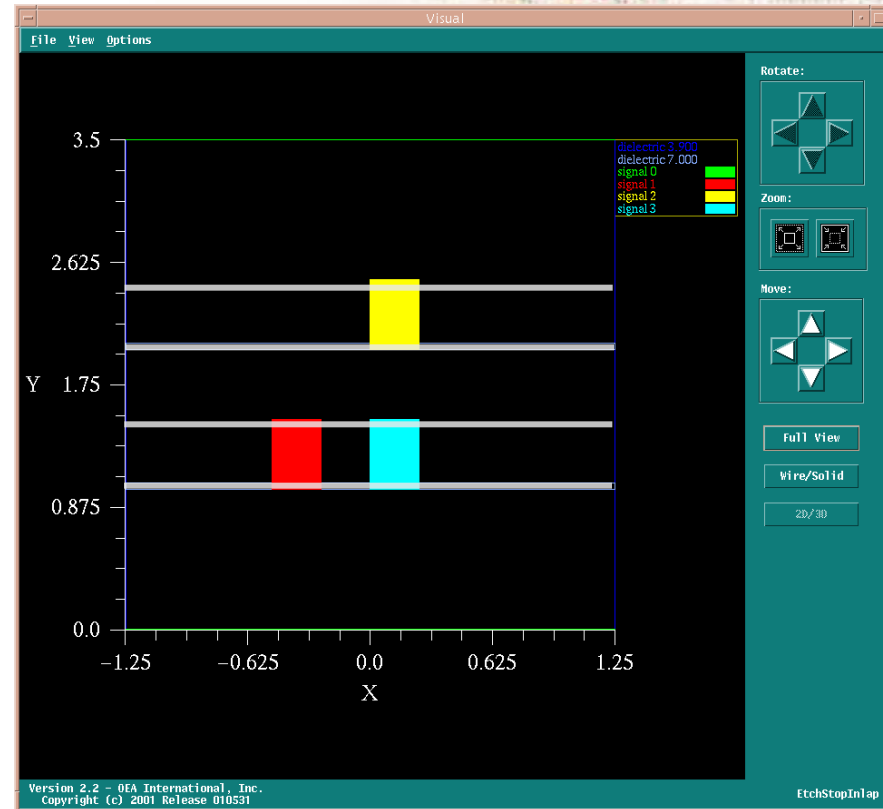
$$\vec{E} = -\nabla V$$



NET-An

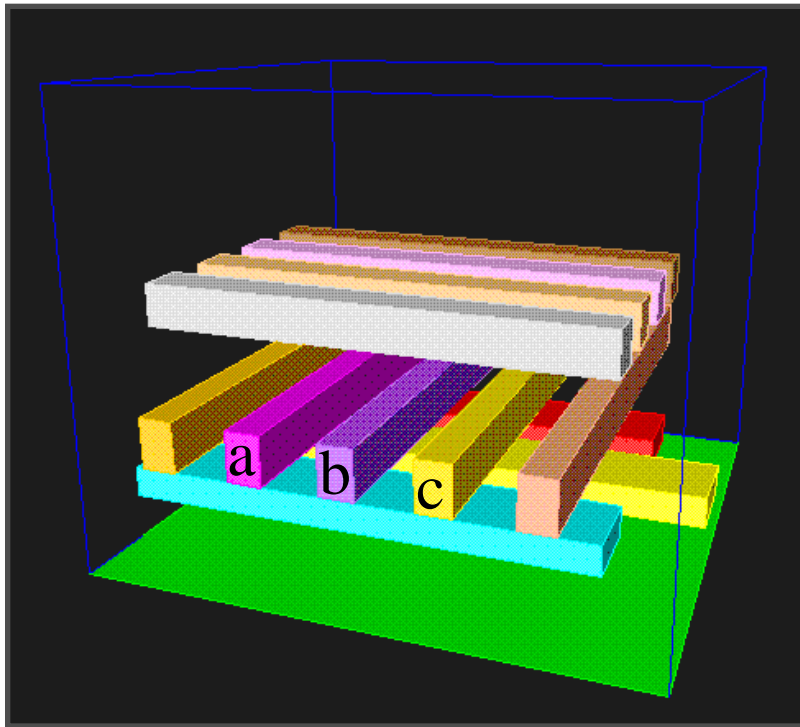
Thin Dielectric Layer Support

- **Numerous dielectric layers**
 - 40 distinct layers not uncommon
 - Etch-stop layers typically $\sim 100 \text{ \AA}$
 - Layer stack averaging or ignoring leads to errors up to 20%
- **True electric fields disproportionately affected**
 - Correct capacitance extraction must include thin dielectric layers
- **NET-AN accurately models thin dielectric layers!**



Comparing 3D Extractors

Small Test Case

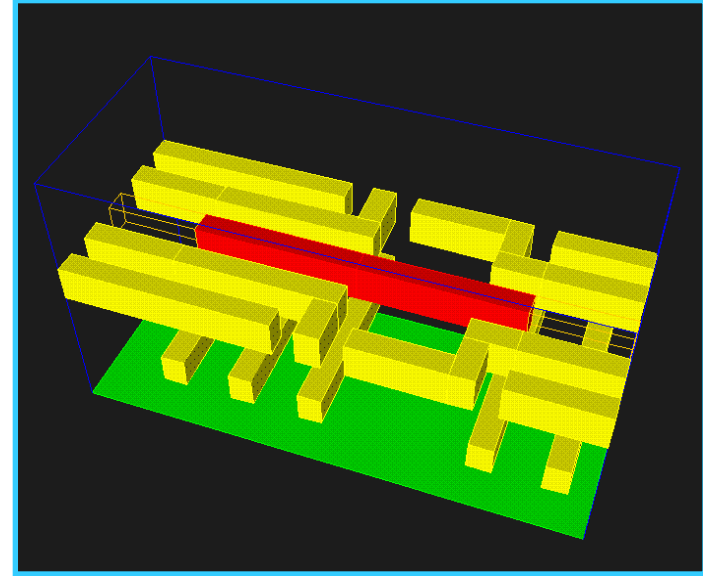
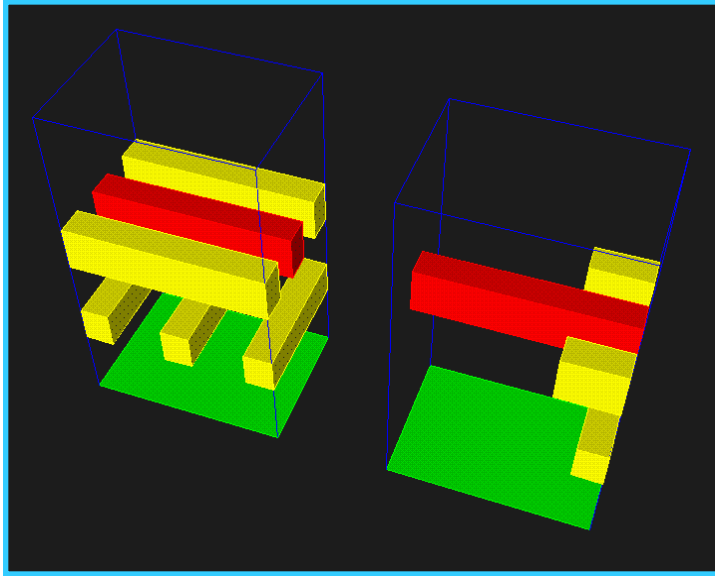


Layer	OEA	Ansoft Maxwell	%Diff	Rapheal	%Diff
M2 a	2.139	2.24	5%	2.17	1%
M2 b	2.140	2.25	5%	2.16	1%
M2 c	2.139	2.24	5%	2.16	1%

Note: Only center nets are used for comparison since other nets on the simulation border are subject to different boundary condition handling between the solvers.

Comparing 3D Extractors

Full 3D vs. 3D Cut & Paste

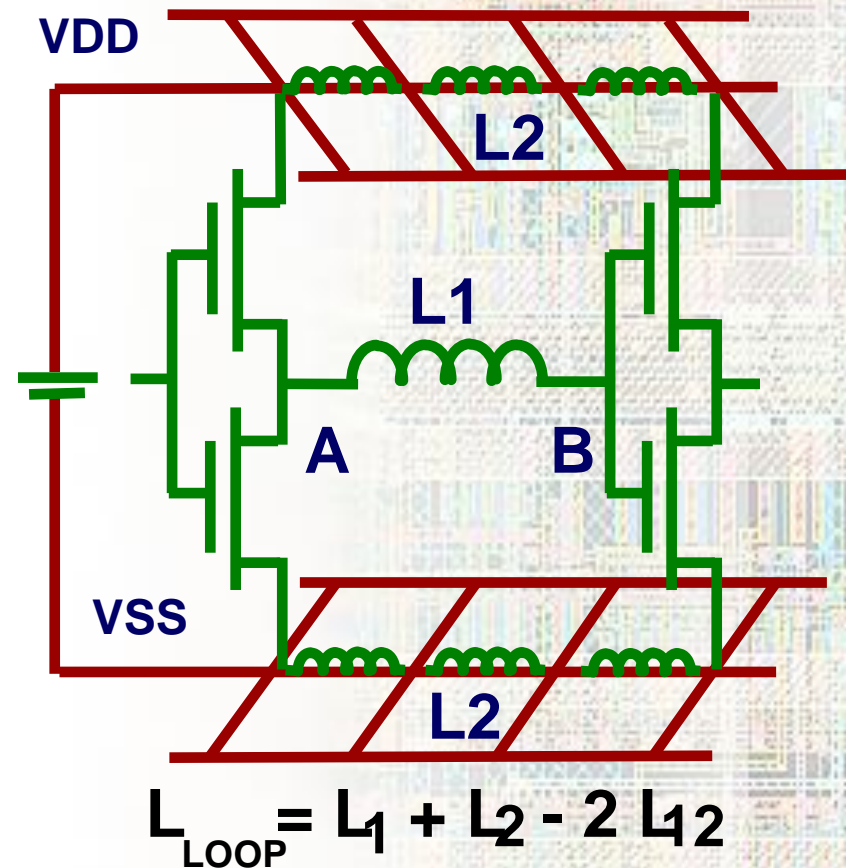


Cut & Paste Method Cap (fF)				Full 3D Method	Cut & Paste Method	Full 3D Method	Cut & Paste Method
	Sect 1	Sect 2	Both	Cap (fF)	Error	Cap (fF)	Error
Window	1μ	1μ	1μ	1μ		2μ	
C11 Full	0.847	0.443	1.290	1.624	21%	1.725	25%
C12	0.847	0.400	1.247	1.603	22%	1.705	27%
C11 gnd	0.001	0.043	0.044	0.021	109%	0.020	118%

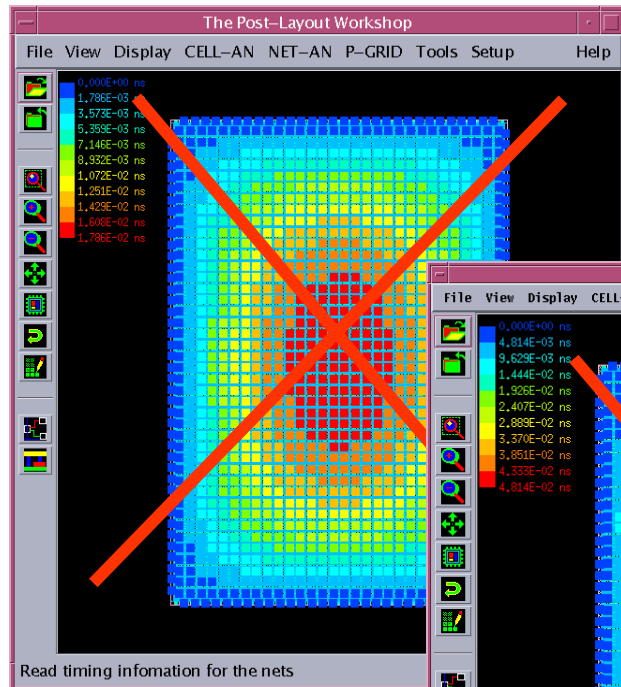
NET-AN

Inductance Support

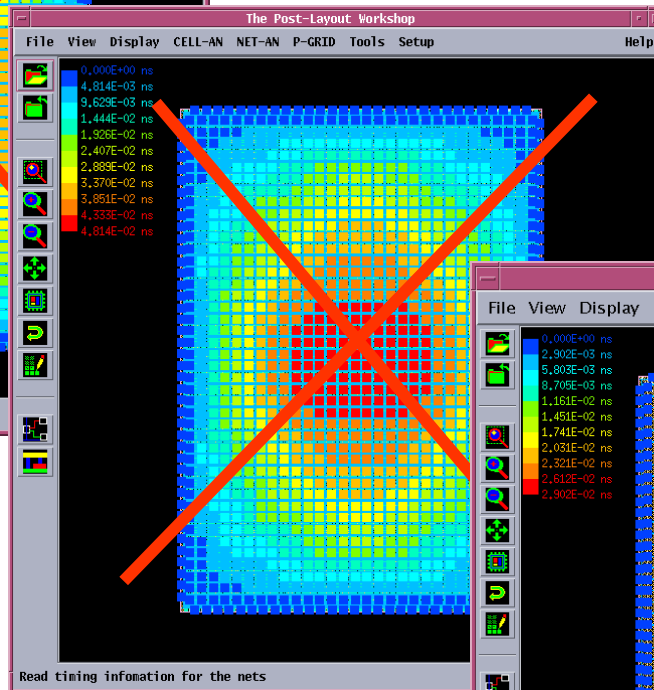
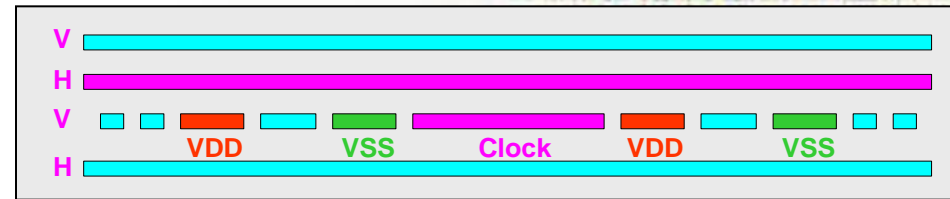
- Partial equivalent element method
 - Self-inductance
 - ◆ Low return path inductance
 - ◆ Low return path coupling
 - ◆ Effective inductance \sim line self-inductance
 - Full Self- and mutual-inductance
 - ◆ Shielded nets with known return path
 - ◆ High return path coupling
 - ◆ Full circuit simulated for highest accuracy



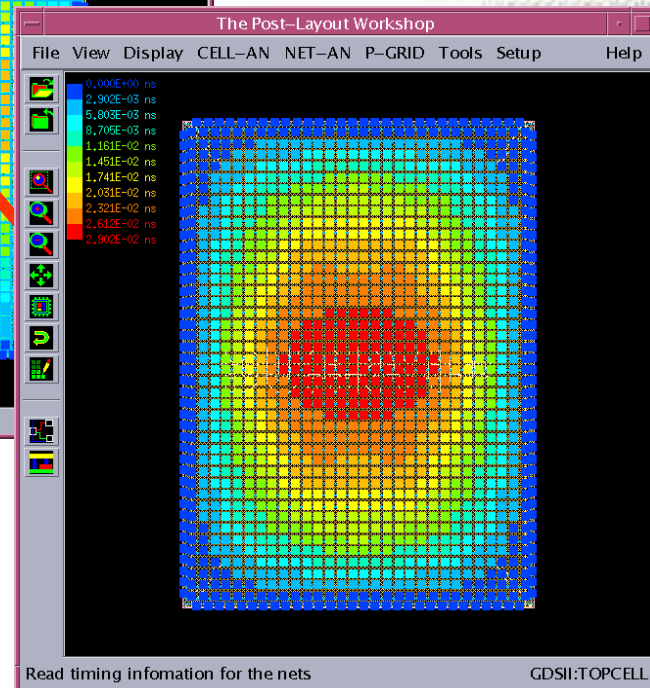
Accurate Inductive Modeling



RC skew
17.9 ps



RCL skew
48.1 ps



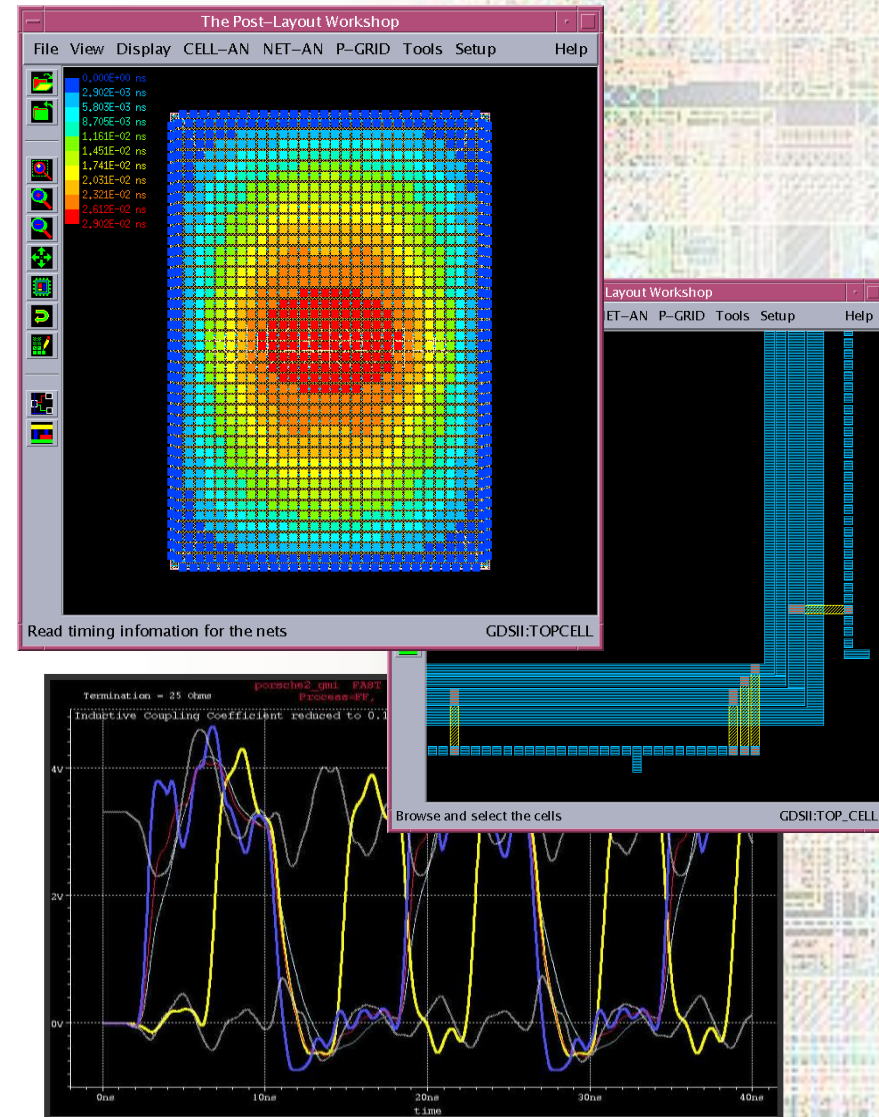
RCLM skew
29.0 ps

Simulated With NET-AN
3D Field Solver Extractor

NET-AN

Extraction Engine for Other OEA Products

- **CLOCK Designer™**
 - 3D Clock Grid Design Planning
 - Fast Cycle Time for Quick What-if Analysis to Optimize Clock Network Width, Spacing, & Buffer Locations
- **BUS-AN™**
 - Interconnect Design Planning
 - 3D Bus Analysis Including Crosstalk
 - 3D Critical Path Analysis
- **RING Designer™**
 - IO Ring Analysis for Simultaneous Switching Noise and Ground Bounce Problems



NET-AN Summary

Defacto Industry Standard for Extraction Accuracy

- More accurate than pattern- or formula-based extractors
- Produces accurate and RLC SPICE decks
 - Width dependent resistivity
 - Full Maxwell 3D resistance and capacitance solution
 - Only solution to include inductance with return path
- Compact SPICE deck generation speeds up simulation
- Fully automated P&R flow for critical net delay analysis